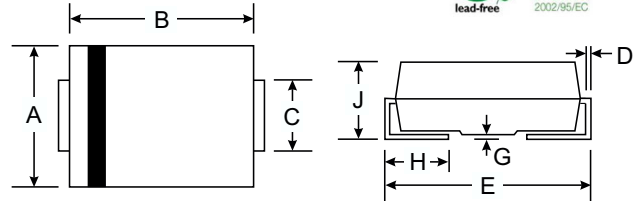


Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 50A Peak
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability Classification Rating 94V-0



Mechanical Data

- Case: SMA/DO-214AC SMB/DO-214AA, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: SMA Weight: 0.064 grams (approx.)
SMB Weight: 0.093 grams (approx.)
- **Lead Free: For RoHS / Lead Free Version**

Dim	SMA		SMB	
	Min	Max	Min	Max
A	2.29	2.92	3.30	3.94
B	4.00	4.60	4.06	4.57
C	1.27	1.63	1.96	2.21
D	0.15	0.31	0.15	0.31
E	4.80	5.59	5.00	5.59
G	0.10	0.20	0.10	0.20
H	0.76	1.52	0.76	1.52
J	2.01	2.62	2.00	2.62
All Dimensions in mm				

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Characteristic	Symbol	SS22	SS23	SS24	SS25	SS26	SS28	SS210	SS2150	SS2200	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	20	30	40	50	60	80	100	150	200	V
Working Peak Reverse Voltage	V _{VRWM}										
DC Blocking Voltage	V _R										
RMS Reverse Voltage	V _{R(RMS)}	14	21	28	35	42	56	70	105	140	V
Average Rectified Output Current @T _L = 75°C	I _O	2.0									A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50									A
Forward Voltage @I _F = 2.0A	V _{FM}	0.55			0.70		0.85		0.90		V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 100°C	I _{RM}	0.5 20									mA
Typical Thermal Resistance (Note 1)	R _{θJL} R _{θJA}	28 88									°C/W
Operating Temperature Range	T _J	-65 to +125									°C
Storage Temperature Range	T _{STG}	-65 to +150									°C

Note: 1. Mounted on P.C. Board with 5.0mm² copper pad area.

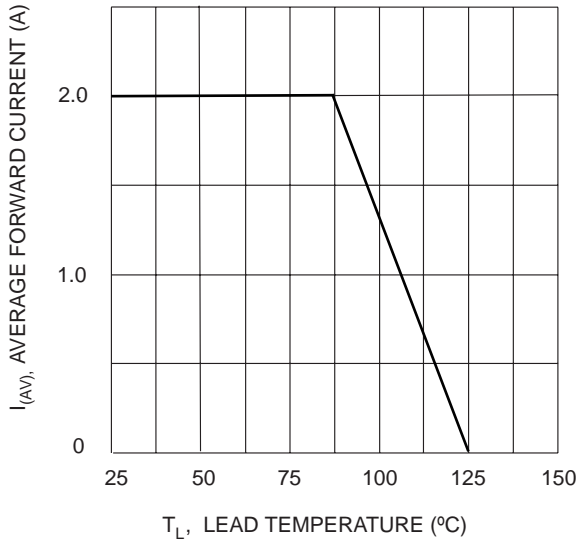


Fig. 1 Forward Current Derating Curve

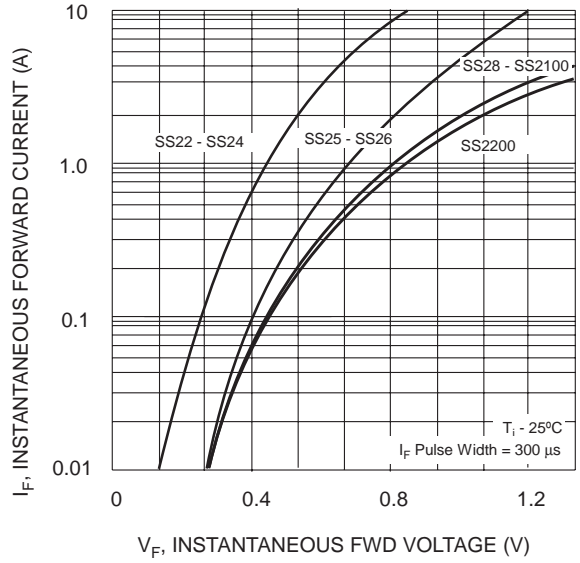


Fig. 2 Typ. Forward Characteristics

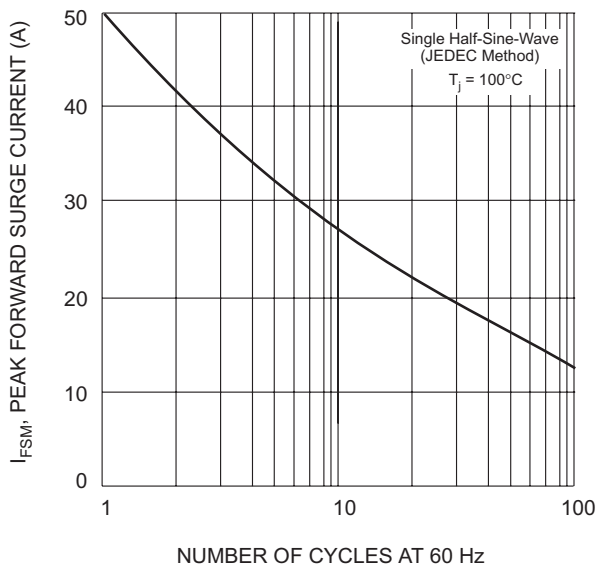


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

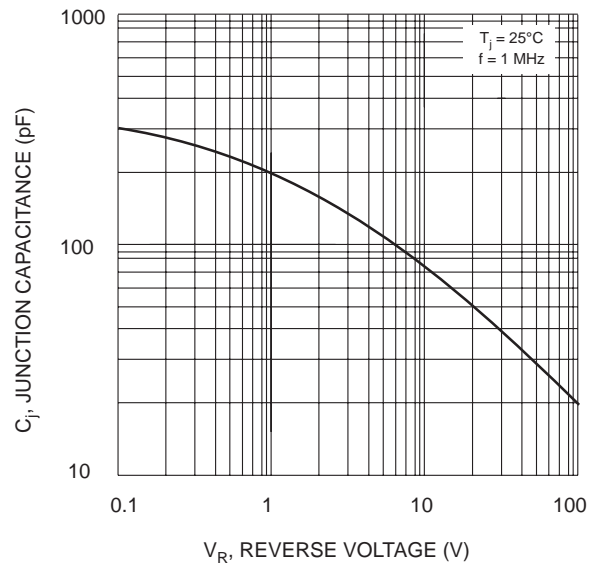


Fig. 4 Typical Junction Capacitance

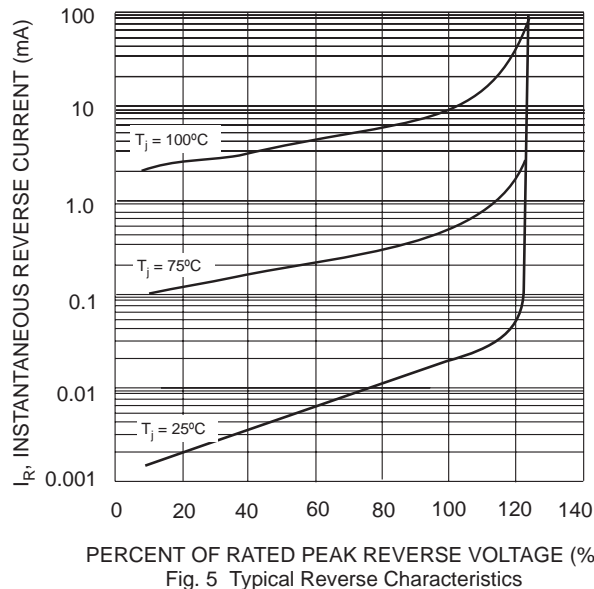


Fig. 5 Typical Reverse Characteristics